



(Translation of a notice from the Japanese Patent Office)

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NOTIFICATION OF REASONS FOR REJECTION

Patent Application No.: 6-38157
Examiner's Notice Date: November 12, 2001
Examiner: T. Kanetaka
Attorneys on Record: Takehiko Suzuye
Applicable Provisions: Section 29^{bis}

This application is rejected on the grounds stated below. Any opinion about the rejection must be filed within 60 days of the mailing date hereof.

REASON

The amendment dated February 22, 2001 was not made within the scope of the original specification or drawing(s) attached to the application for the following reason. Therefore, the present application fails to meet the requirement under Section 17 (2) of the Patent Law.

REMARKS

(a)

The amended claims 1, 4, 8, 9 and 11 recite that the buffer layer has a number of holes and an average thickness of 3-10 nm.

However, the original specification or drawing(s) only discloses the buffer layer as porous (for example, paragraph 7) and the average thickness as less than 10 nm (paragraph 8).

Therefore, the feature that the buffer layer has a number of holes and an average thickness of 3-10 nm is not disclosed in the original specification or drawing(s), nor is it considered to be directly and unambiguously derived therefrom.

Consequently, the above amendment introduces new matter.